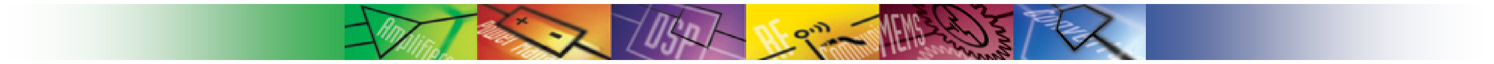

Product / Package Information

Package	PLCC
Body Size	
Lead Count	20
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.04 E-01	87.7	877000	57.45	574528
Thermosets	Epoxy Resin	Proprietary	2.30 E-02	5.0	50000	3.28	32755
Thermosets	Phenol Resin	Proprietary	2.30 E-02	5.0	50000	3.28	32755
Thermosets	Epoxy Cresol Novolac	29690-82-2	9.21 E-03	2.0	20000	1.31	13102
Other inorganic materials	Carbon Black	1333-86-3	1.38 E-03	0.3	3000	0.20	1965
Subtotal			4.60 E-01	100	1000000	65.51	655107

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.12 E-01	99.90	999000	30.22	302154
Copper & its alloys	Zirconium	7704-99-6	2.13 E-04	0.10	1000	0.03	302
Subtotal			2.13 E-01	100.00	1000000	30.25	302456

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.74E-03	100.0	1000000	0.25	2480

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.01E-02	100.0	1000000	1.44	14366

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.92 E-04	99.99	1000000	0.08	842

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.25E-02	100.0	1000000	1.78	17809

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.42 E-03	75.0	750000	0.49	4871
Thermoset	Epoxy Resin	9003-36-5 / 30583-72-3	9.13 E-04	20.0	200000	0.13	1299
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	1.14 E-04	2.5	25000	0.02	162
Other organic materials	Phenolic hardener	92-88-6	6.85 E-05	1.5	15000	0.010	97
Other organic materials	Butyl cellosolve acetate	112-07-2	4.57 E-05	1.0	10000	0.006	65
Subtotal			4.57 E-03	100	1000000	0.65	6495

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	1.89 E-04	60.4	604000	0.027	269
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	8.76 E-05	28.0	280000	0.012	125
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	3.13 E-05	10.0	100000	0.004	45
Other organic materials	Ethylbenzene	100-41-4	3.13 E-06	1.0	10000	0.00045	4
Other organic materials	Xylene	1330-20-7	1.88 E-06	0.6	6000	0.00027	2.7
Subtotal			3.13 E-04	100.0	1000000	0.04	445

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.03 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
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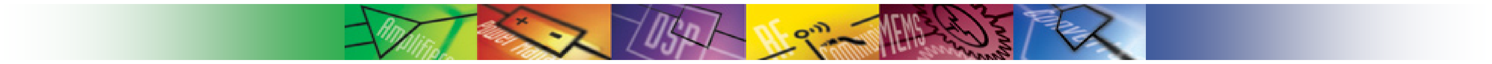
ANALOG DEVICES



Product / Package Information

Package	PLCC
Body Size	
Lead Count	20
Terminal Finish	85Sn15Pb

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

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				Percentage (%)	PPM	Percentage (%)	PPM
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Thermosets	Epoxy Resin	Proprietary	2.30 E-02	5.0	50000	3.28	32755
Thermosets	Phenol Resin	Proprietary	2.30 E-02	5.0	50000	3.28	32755
Thermosets	Epoxy Cresol Novolac	29690-82-2	9.21 E-03	2.0	20000	1.31	13102
Other inorganic materials	Carbon Black	1333-86-3	1.38 E-03	0.3	3000	0.20	1965
Subtotal			4.60 E-01	100	1000000	65.51	655107

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Copper & its alloys	Zirconium	7704-99-6	2.13 E-04	0.10	1000	0.03	302
Subtotal			2.13 E-01	100.00	1000000	30.25	302456

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.74E-03	100.0	1000000	0.25	2480

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.58E-03	85.0	850000	1.22	12211
Tin & its alloys	Lead	7439-92-1	1.51E-03	15.0	150000	0.22	2155
Subtotal			1.01E-02	100.0	1000000	1.44	14366

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.92 E-04	99.99	1000000	0.08	842

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.25E-02	100.0	1000000	1.78	17809

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.42 E-03	75.0	750000	0.49	4871
Thermoset	Epoxy Resin	9003-36-5 / 30583-72-3	9.13 E-04	20.0	200000	0.13	1299
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	1.14 E-04	2.5	25000	0.02	162
Other organic materials	Phenolic hardener	92-88-6	6.85 E-05	1.5	15000	0.010	97
Other organic materials	Butyl cellosolve acetate	112-07-2	4.57 E-05	1.0	10000	0.006	65
Subtotal			4.57 E-03	100	1000000	0.65	6495

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	8.76 E-05	28.0	280000	0.012	125
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	3.13 E-05	10.0	100000	0.004	45
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Other organic materials	Xylene	1330-20-7	1.88 E-06	0.6	6000	0.00027	2.7
Subtotal			3.13 E-04	100.0	1000000	0.04	445

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.03 E-01**	**100.00**	**1000000**

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ANALOG DEVICES